

MODEL: HSB41-303014P | DESCRIPTION: HEAT SINK

FEATURES

- BGA design
- push pins

RoHS

- aluminum alloy
- black anodized finish



MODEL	thermal resistance'				
	© 75°C ∆T, nat conv (°C/W)	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)	@ 1 W, 400 LFM [°C/W]	dissipation¹ @ 75°C ∆T, nat conv [W]
HSB40-252510P	12.63	15.1	4.3	2.9	5.94

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)				
Power (W)	Natural Conv.	200 LFM	400 LFM		
0	0	0	O		
1	15.1	4.3	2.9		
2	29.0	8.9	5.9		
3	41.9	12.8	8.6		
4	54.0	17.1	11.6		
5	65.3	21.3	14.4		
6	75.9	25.7	17.3		
7	86.2	30.2	20.2		
8	96.2	34.2	23.0		
9	105.4	38.7	25.9		
10	115.0	42.9	28.9		

Mounting Surface Temperature Rise Above Ambient (°C) 140 120 Without Airflow 200 LFM 100 400 LFM 80 60 40 20 Ο 0 2 4 6 8 12 10 Heat Dissipated (W)

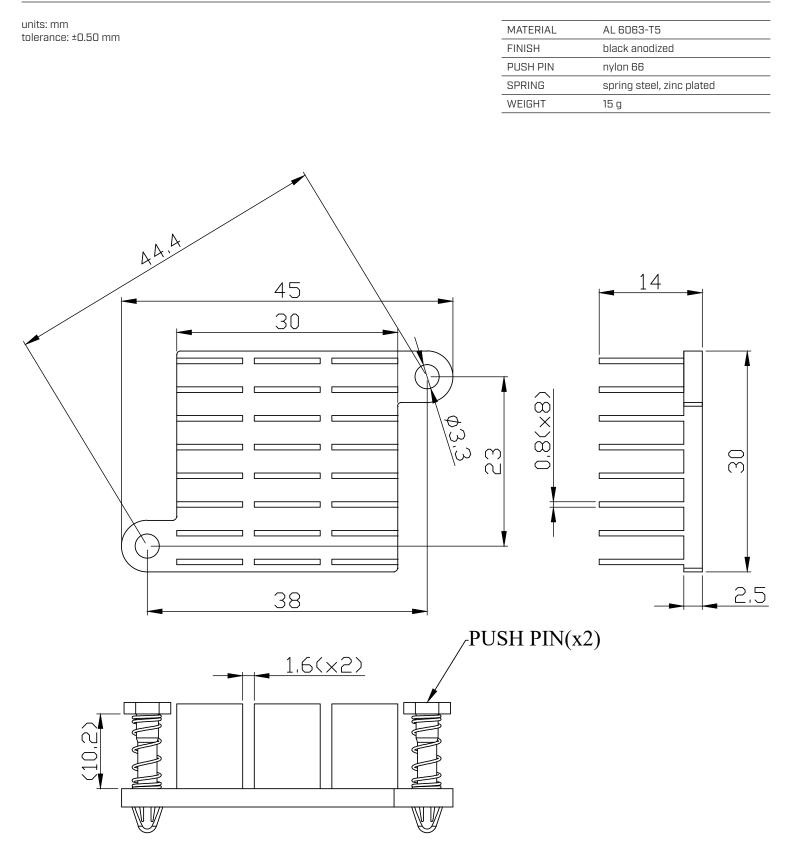
Ths: "hot spot" temperature measured on the heatsink Ta: ambient temperature

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MECHANICAL DRAWING

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REVISION HISTORY

rev.	description	date
1.0	initial release	03/01/2024

The revision history provided is for informational purposes only and is believed to be accurate.

CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.



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